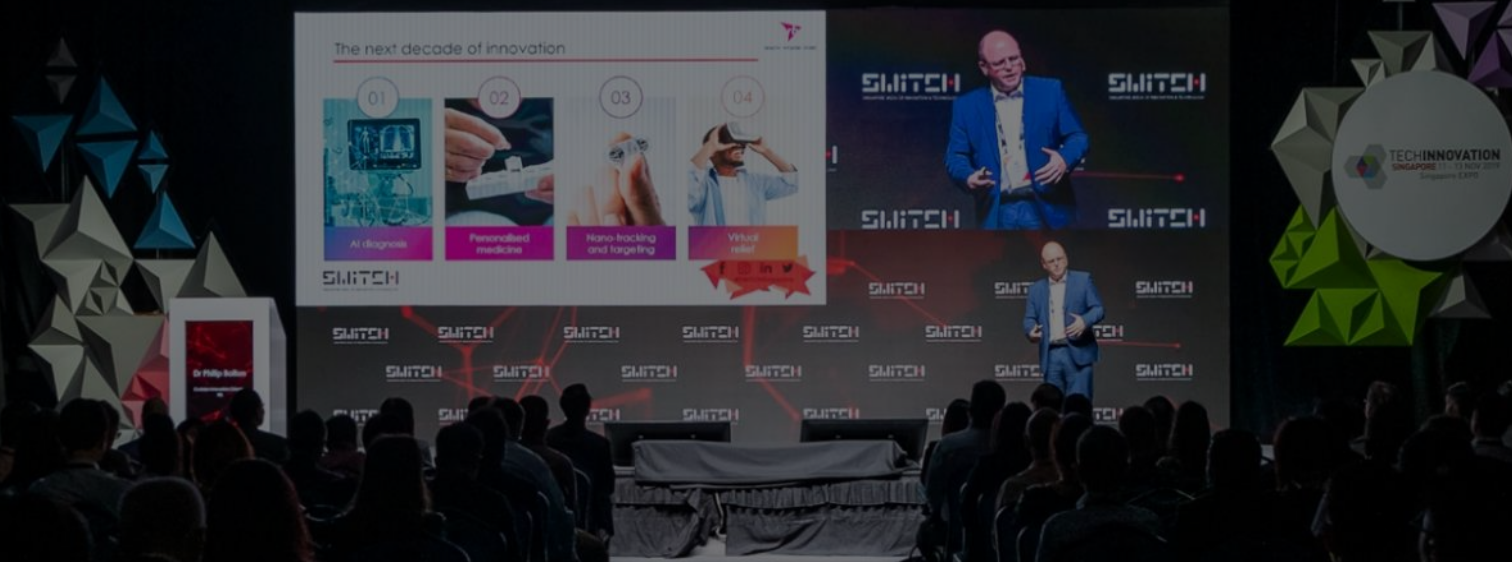




TechInnovation 2020

Discover. Connect. Collaborate

Exhibition Package



Organised by



A Part of



About TechInnovation

TECHINNOVATION is a premier technology-to-industry matching event organised by IPI.

It brings together international technology providers and enterprises to accelerate the commercialisation of emerging technologies, seed licensing opportunities and foster open innovation collaborations.

The 9th edition of TechInnovation will be held as part of SWITCH 2020 (Singapore Week of Innovation and TeCHnology).

We're Going Digital!

This year, TechInnovation 2020 will be a 100% digital event running 24 hours over 5 days. Exhibitors and attendees across all time zones will be able to participate and network with each other virtually.



What to Expect at TechInnovation 2020



INNOVATION INSIGHTS

Thought leaders and industry experts share emerging technology trends, open innovation best practices and more.



CROWDSOURCING

Large corporations engage the innovation community for technology solutions and partnerships to solve business challenges through an open innovation platform.

If you have the solution, step forward with your proposal for an opportunity to collaborate with the corporations.



CROWDPITCHING

Innovators showcase and pitch enabling technologies for commercialisation or co-development to technology seekers.

Shortlisted exhibitors get 5-min slot to pitch their Tech Offers to international technology seekers in one of the four technology domains at Crowdpitching webinars.



TECHNOLOGY MATCHING

Participants that are seeking partnerships via R&D collaboration, technology commercialisation or licensing can connect to potential collaborators through our B2B technology matching service. Meeting slots are available over 5 full days.

Tech Expert clinics are also open to start-ups and SMEs looking for technical advice to support their product development.

Technology Themes & Focus Areas



DIGITAL ECONOMY

- Internet of things & sensors
- Augmented & Virtual Reality (AR/VR)
- Cybersecurity
- Artificial Intelligence
- Blockchain & Distributed Ledger Technologies
- Edge Computing

HEALTH & PERSONAL CARE

- Diagnostics
- Medical devices
- Therapeutic
- Skin care
- Digital health

URBAN SOLUTIONS & SUSTAINABILITY

- Green building
- Renewable energy
- Solid waste management
- Industrial waste water treatment

FOOD & NUTRITION

- Alternative protein
- Shelf life extension
- Upcycling of food waste
- Re-formulation

TechInnovation Programme Overview (7 – 9 Dec)



Time (GMT +8)	Day 1 (7 Dec)	Day 2 (8 Dec)	Day 3 (9 Dec)
1st Half of Webinars 1000 – 1400 hr	Opening & Plenary “Open Innovation in Uncertain Times” Talks by thought leaders followed by panel discussion	Crowdsourcing for Corporates (Sustainability I) Sharing of Challenge Statements by Corporates seeking solutions	Plenary “Catalysing Innovation With Design” A Design-led Innovation segment hosted by Design Council Singapore Design Runway Sharing of good design projects and ideas for collaboration with industry Design Think Tank Sharing of Challenge Statements by corporates and agencies seeking design solutions
	Crowdsourcing for Corporates Sharing of Challenge Statements by Corporates seeking solutions	Crowdsourcing for Corporates (Sustainability II) Sharing of Challenge Statements by Corporates seeking solutions	
2nd Half of Webinars 1400 – 1800 hr	Crowdpitching for Exhibitors <ul style="list-style-type: none"> Digital Economy Urban Solutions & Sustainability 	Crowdpitching for Exhibitors <ul style="list-style-type: none"> Health & Personal Care Food & Nutrition 	Crowdpitching by Country Special segment on pitching of tech offers co-hosted with country partner
	Crowdpitching by Country Special segment on pitching of tech offers co-hosted with country partner	Crowdpitching by Country Special segment on pitching of tech offers co-hosted with country partner	

Programme and timing is subject to change.

Exhibiting at TechInnovation

Excellent Networking and Collaboration Opportunities

- The largest and most established technology marketplace & matching event in Singapore & Southeast Asia
- Network with C-level executives and decision makers seeking enabling technologies
- B2B meetings with potential collaborators facilitated by IPI



Create Awareness and Interest for your Technology Offers

- Showcase your Tech Offers to seek collaboration partners
- Pitch your Tech Offers at Crowdpitching webinars for commercialisation and collaboration opportunities
- Selected Tech Offers will be published on IPI's Innovation Marketplace for 2 years after the event for greater international exposure



TechInnovation Exhibition Package (7 – 11 Dec)



Exhibitors' Entitlements	Basic Package S\$200	Standard Package \$800
Package is Suitable For	SME, Startup, Researcher, Inventor	Tech Transfer Office, Research Institute, Centre of Innovation, Incubator & Accelerator, Innovation Agency and Enterprise with more Tech Offers
Exhibition Format (digital)	Exhibitor's webpage to display company profile and showcase Tech Offers	
No. of Technology Offer Listing	Up to 2 Tech Offers	Up to 12 Tech Offers
No. of Exhibitor Login Accounts	Up to 2 accounts	Up to 10 accounts
Tech Matching & B2B Meetings	Self-service meeting bookings between Exhibitors & Attendees Exhibitors have access to Tech Needs information of Attendees (if made available by Attendees) Tech Matchings facilitated by IPI	
Present Tech Offer at Crowdpitching Webinar	May nominate 1 Tech Offer for pitching subject to shortlisting by IPI (Deadline to nominate Tech offer by 9 Nov)	
Featuring of Tech Offers at IPI's Portal	Selected Tech Offers will be published in Innovation Marketplace at IPI's portal after the event for 2 years for more international exposure	

Ask us about an option to exhibit at both TechInnovation and SWITCH for a small upgrade price.

Your TechInnovation “Digital Booth”

Display your Corporate Information

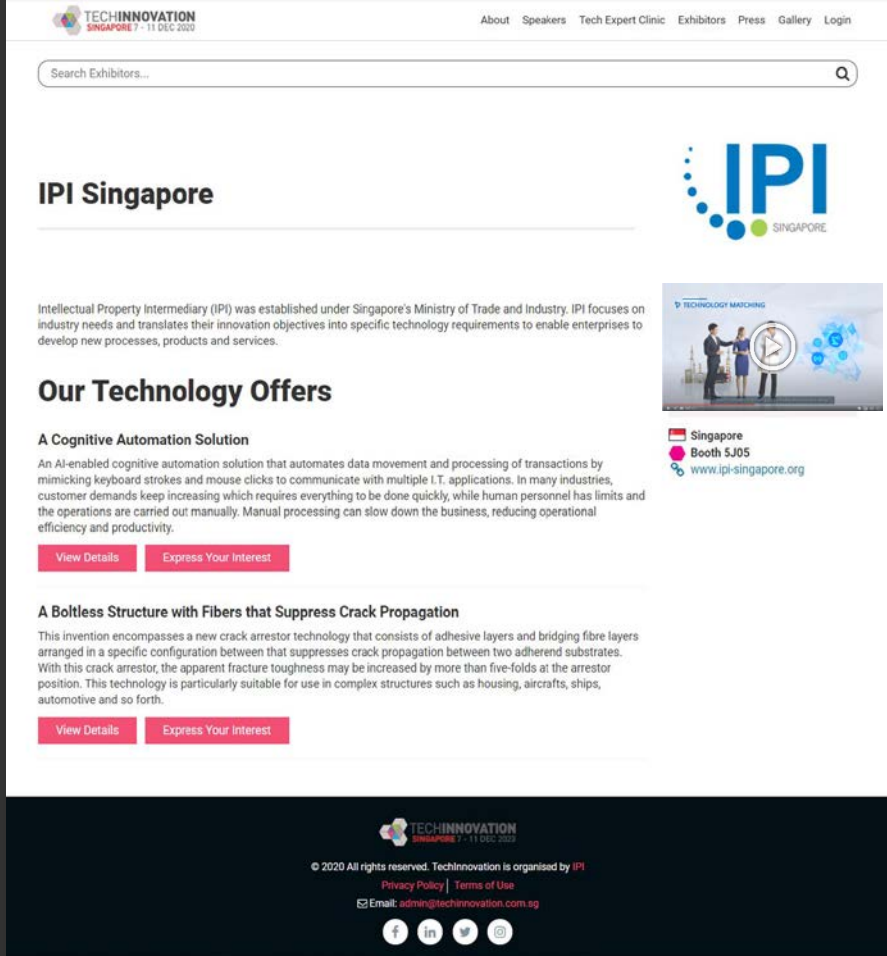
- Each exhibitor gets a webpage
- Company name & logo
- 50-word profile
- Company video link

Showcase your Tech Offers

- 2 Tech Offers for Basic Package
- 12 Tech Offers for Standard Package
- Detailed Tech Offer descriptions

Easy to search and navigate by visitors to

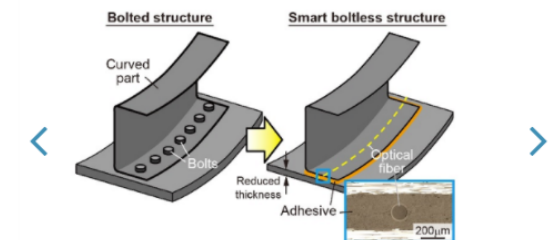
- Search by exhibitor
- Search by Tech Offer
- Book meetings with you



The screenshot shows the IPI Singapore digital booth webpage. At the top, there is a navigation menu with links for 'About', 'Speakers', 'Tech Expert Clinic', 'Exhibitors', 'Press', 'Gallery', and 'Login'. Below the menu is a search bar labeled 'Search Exhibitors...'. The main header features the 'IPI SINGAPORE' logo. The content area includes a brief description of IPI as an Intellectual Property Intermediary established under Singapore's Ministry of Trade and Industry. It highlights 'Our Technology Offers', specifically 'A Cognitive Automation Solution' and 'A Boltless Structure with Fibers that Suppress Crack Propagation'. Each offer has a 'View Details' and 'Express Your Interest' button. A 'Technology Matching' section shows a video thumbnail and a badge for 'Singapore Booth 5J05' with the website 'www.ipi-singapore.org'. The footer contains copyright information, contact details, and social media icons.

A Boltless Structure with Fibers that Suppress Crack Propagation

Figure 1



Abstract/Technology Overview

This invention encompasses a new crack arrestor technology that consists of adhesive layers and bridging fibre layers arranged in a specific configuration between that suppresses crack propagation between two adherend substrates. With this crack arrestor, the apparent fracture toughness may be increased by more than five-folds at the arrestor position. This technology is particularly suitable for use in complex structures such as housing, aircrafts, ships, automotive and so forth.

Technology Features, Specifications and Advantages

The crack arrestor consists of the bonding the two 0° composite layer between the two adherend substrate in an interlocking 'x' shaped configuration (Figure 2), with the 90° reinforcement composite layer inserted between the interlocking members of the two earlier composite layer to form a final configuration illustrated in Figure 3. Appropriate adhesive is used to bond the various surfaces (i.e. interlocking composite to adherend substrate; interlocking composite to interlocking composite; interlocking composite to reinforcing composite).

As a crack in the adherend substrate propagates towards the arrestor, the crack is robustly entrapped in the arrestor by virtue of the surface ply-drop of the adherends. As the crack approaches the arrestor, the 0° interlocking composite layers bridges the crack and suppresses further crack opening as seen in Figure 4. The 90° layer acts as a reinforcement and prevents the interlocking layer from further peeling off as the crack propagates, effectively increasing the fracture toughness.

How To Exhibit At TechInnovation

Step 1: Register at TechInnovation Platform

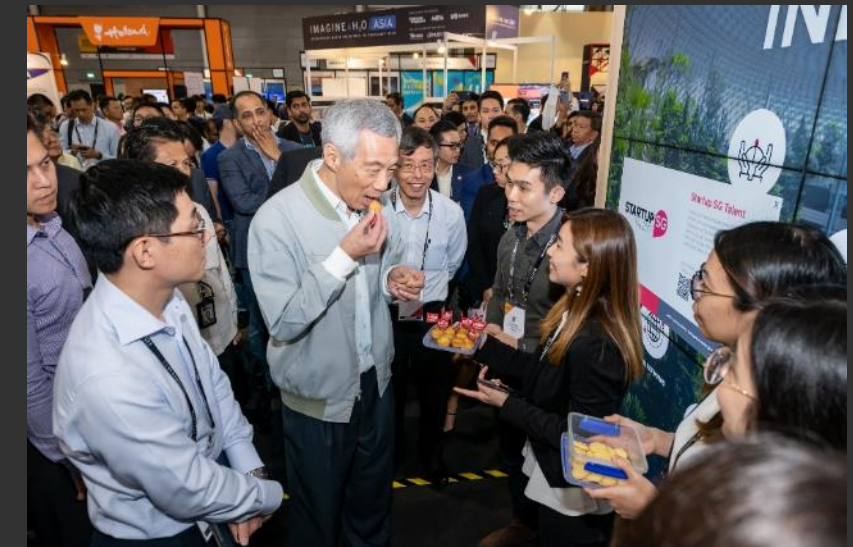
- Visit www.techinnovation.com.sg to register your interest to exhibit
- Select the **Basic** or **Standard** Package
- Provide your company profile and brief description of Tech Offers to showcase

Step 2: Submit Your Tech Offers

- Once your registration is accepted, login to submit your Tech Offer write-ups
- Nominate your Tech Offer for Crowdpitching in one of 4 technology themes
- Approved Tech Offers will be listed on TechInnovation platform from 9 Nov

Important Dates for Exhibitors

- Start of exhibitor registration: **21 Sep**
- Deadline to submit Tech Offers: **9 Nov**
- Deadline to nominate Tech Offer for Crowdpitching: **9 Nov**
- Deadline to register: **23 Nov** (or when the exhibition slots are fully taken up)





Contact us

Visit www.techinnovation.com.sg for the latest updates and [FAQ](#)

For enquiry on exhibition packages, please contact
admin@techinnovation.com.sg for more information

